

# MIP2L40MY

## Silicon MOS FET type integrated circuit

### ■ Features

- Reducing the average noise  
Adding a frequency jitter function to MIP2E/3E\* series to dramatically reduce the average noise and simplify EMI parts
- Stabilization of maximum electric power by input correction  
Correcting the input voltage dependency of I LIMIT reduces the input voltage dependency of maximum output current
- Overheating protection function  
Changed from stopping in latch mode to self reset type
- Protecting function  
Overload protection, overheat protection

### ■ Applications

- Flat-screen TV, audio and others

### ■ Package

- Code  
TO-220-A2
- Pin Name  
1. CONTROL  
2. SOURCE  
3. DRAIN

### ■ Marking Symbol: MIP2L4MY

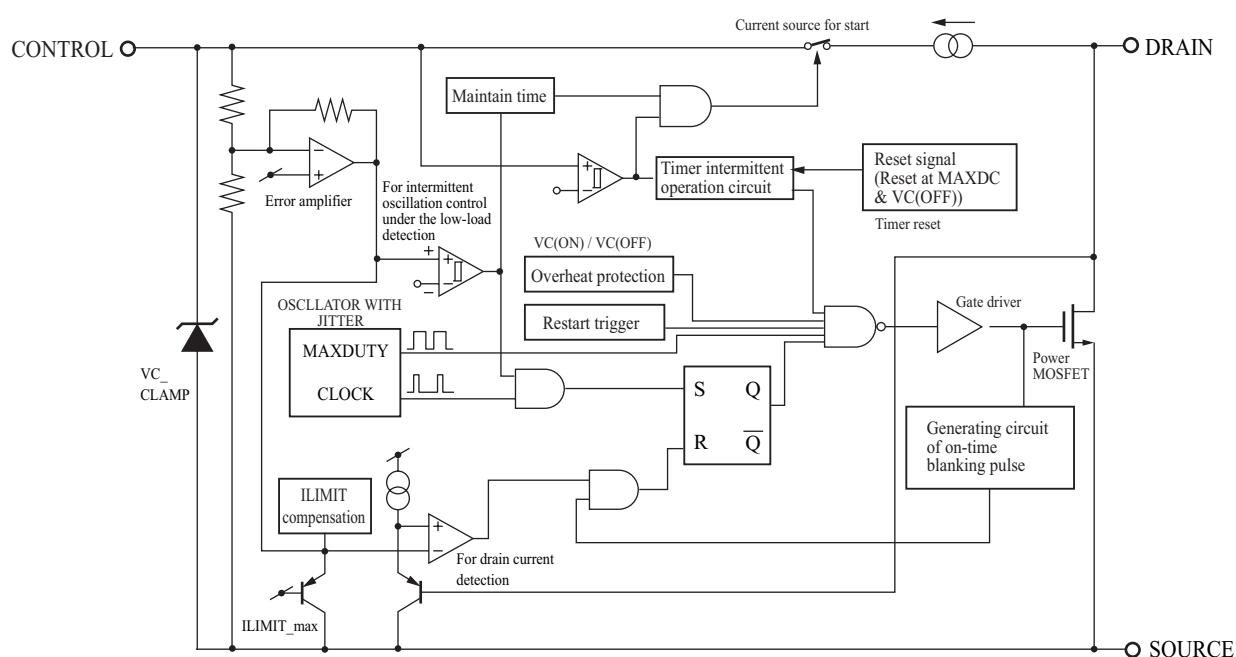
### ■ Absolute Maximum Ratings $T_a = 25^{\circ}\text{C} \pm 3^{\circ}\text{C}$

Parameter	Symbol	Rating	Unit
DRAIN voltage	VD	-0.3 to +700	V
CONTROL voltage	VC	-0.3 to +8	V
Output peak current *	IDP	2.7	A
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*: The guarantee within the following pulse width.

Leading edge blanking delay + Current limit delay  $t_{on}(\text{BLK}) + t_d(\text{OCL})$

### ■ Block Diagram



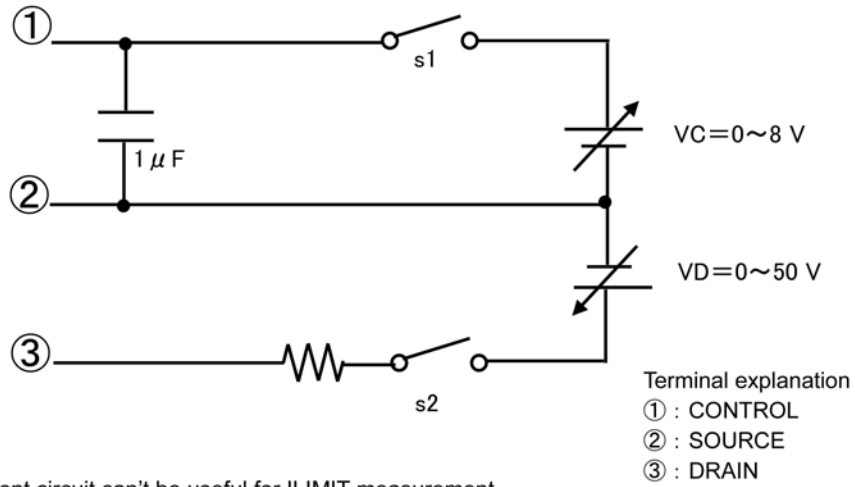
■ Electrical Characteristics  $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Control functions</b>						
Output frequency	fosc	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$	92	100	108	kHz
Jitter frequency deviation	$\Delta f$	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$ * Fig. 5		5.5		kHz
Jitter frequency modulation rate *	fM	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$ * Fig. 5		270		Hz
Maximum duty cycle	MAXDC	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$	50	53	56	%
PWM gain *	GPWM	$VC = VC(\text{CNT})$		12.5		dB
Before auto-restart current	IC(SB)1	$VC < VC(\text{ON})$ , $VD = 5 \text{ V}$	0.2	0.5	0.8	mA
After off-state current	IC(SB)2	$VC > VC(\text{CNT})$ , $VD = 5 \text{ V}$	0.2	0.5	0.8	mA
Operating current	IC(OP)	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$	0.25	0.7	1.15	mA
Auto-restart threshold voltage	VC(ON)	$VD = 5 \text{ V}$	5.75	6.25	6.75	V
UV lockout threshold voltage	VC(OFF)	$VD = 5 \text{ V}$	4.35	4.8	5.25	V
Auto-restart maintain voltage	VC_m	$S1 = \text{OPEN}$	4.95	5.45	5.95	V
Auto-restart maintain time	Tm	$S1 = \text{OPEN}$		45		ms
Auto-restart hysteresis voltage	$\Delta VC$	$VC(\text{ON}) - VC(\text{OFF})$	1.05	1.45	1.85	V
Control clamp voltage	VC(CLP)	$IC = 3 \text{ mA}$	6.2	6.8	7.4	V
Auto-restart duty cycle	TSW/TTIM	$S1 = \text{OPEN}$ * Fig. 4		12		%
Auto-restart frequency	fTIM	$S1 = \text{OPEN}$ * Fig. 4		2.6		Hz
Control pin charging current	IC(CHG)1	$VC = 0 \text{ V}$ , $VD = 50 \text{ V}$	-14	-9	-6	mA
	IC(CHG)2	$VC = 5 \text{ V}$ , $VD = 50 \text{ V}$	-11.2	-5.7	-2.4	mA
Control pin voltage	VC(CNT)	$VD = 5 \text{ V}$	5.3	5.9	6.5	V
Control pin voltage hysteresis *	$\Delta VC(\text{CNT})$	$VD = 5 \text{ V}$		10		mV
<b>Circuit protections</b>						
Self protection current limit	ILIMIT	Duty = 30% * Fig. 1, 2	1.24	1.35	1.46	A
ILIMIT modified coefficient	R_slope	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ * Fig. 1, 2		37		mA/ $\mu\text{s}$
Leading edge blanking delay *	ton(BLK)		240	300	360	ns
Current limit delay *	td(OCL)		140	210	280	ns
Thermal shutdown temperature *	TOTP		130	140	150	$^\circ\text{C}$
Thermal shutdown temperature hysteresis *	$\Delta\text{TOTP}$			70		$^\circ\text{C}$
<b>Output</b>						
Power-up reset threshold voltage *	VCreset		1.8	2.6	3.5	V
ON-state resistance	RDS(ON)	$ID = 0.2 \text{ A}$		5.2	6.7	$\Omega$
OFF-state leakage current	IDSS	$VD = 650 \text{ V}$ , $VC = 6.5 \text{ V}$		10	20	$\mu\text{A}$
Breakdown voltage	VDSS	$ID = 100 \mu\text{A}$ , $VC = 6.5 \text{ V}$	700			V
Rise time	tr	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$ * Fig. 3		95		ns
Fall time	tf	$VC = VC(\text{CNT}) - 0.2 \text{ V}$ , $VD = 5 \text{ V}$ * Fig. 3		30		ns
<b>Supply voltage characteristics</b>						
Drain supply voltage	VD(MIN)	$S1 = \text{OPEN}$	36			V

Note) \*: Design guaranteed item

■ Electrical Characteristics (continued)  $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

1. Measurement circuit



\* This measurement circuit can't be useful for ILIMIT measurement

2. Figure 1. Measurement circuit 2

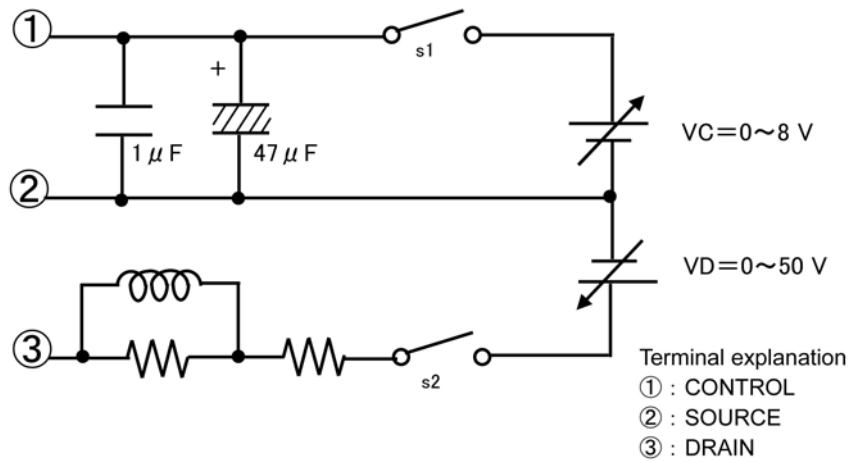
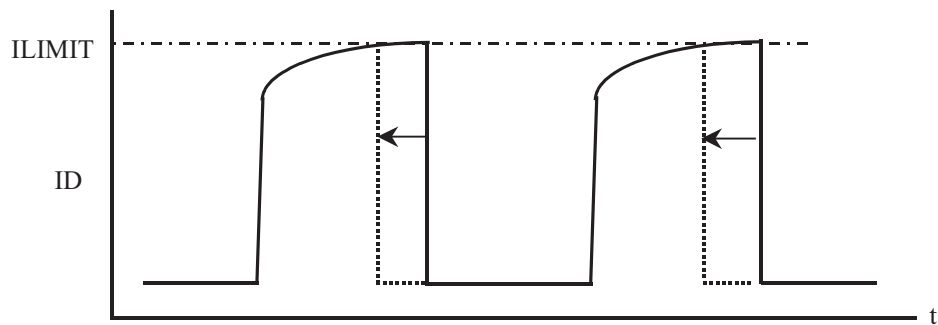


Figure 2. ILIMIT measurement



$$R_{\text{slope}} = \{(\text{ILIMIT at Duty} = 30\%) - (\text{ILIMIT at Duty} = 20\%)\} / \{(\text{Ton at Duty} = 30\%) - (\text{Ton at Duty} = 20\%)\}$$

■ Electrical Characteristics (continued)  $T_C = 25^{\circ}\text{C} \pm 3^{\circ}\text{C}$

2. Figure 3.  $t_r$ ,  $t_f$  measurement

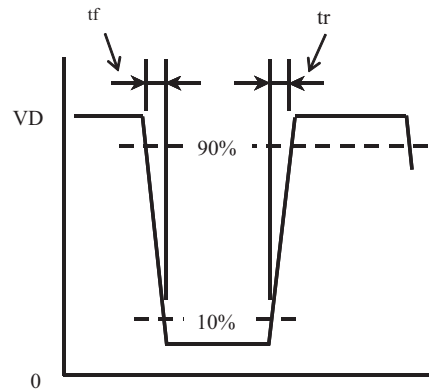


Figure 4.  $V_{C\_m}$ ,  $T_m$ ,  $T_{TSW}$ ,  $T_{TIM}$ ,  $f_{TIM}$  measurement

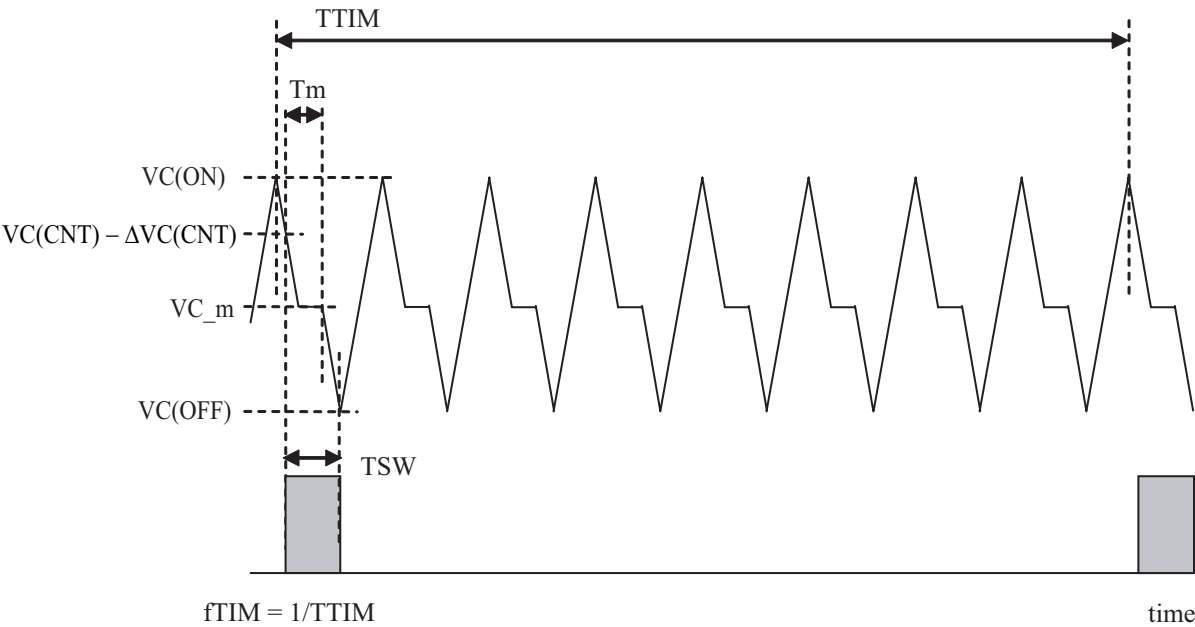
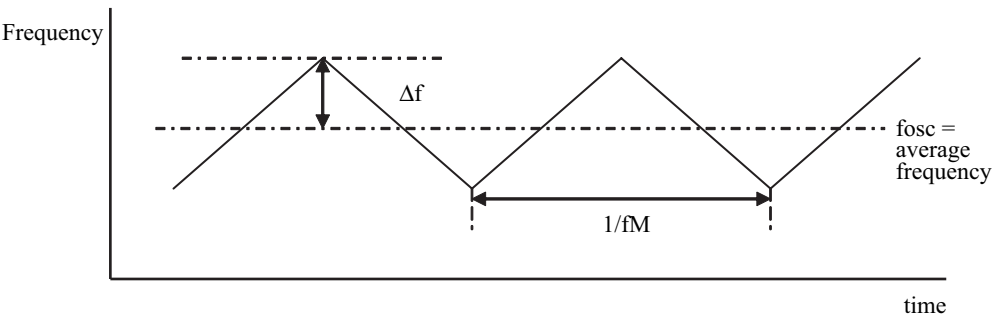


Figure 5.  $\Delta f$ ,  $f_M$  measurement



**■ Usage Notes**

Connect a Ceramic Capacitor (over 0.1  $\mu$ F) between CONTROL and SOURCE.

The IPD has risks for break-down or burst or giving off smoke in following conditions. Avoid the following use.

Fuse should be added at the input side or connect zener diode between control pin and GND, etc as a countermeasure to pass regulatory Safety Standard. Concrete countermeasure could be provided individually. However, customer should make the final judgment.

- (1) Reverse the DRAIN pin and SOURCE pin connection to the power supply board.
- (2) DRAIN pin short to CONTROL pin.
- (3) DRAIN pin short to SOURCE pin.

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